

UniGap 10000NS

High Performance Gap Filler



UniGap 10000NS is a high performance, non-silicone thermal gap filler. This compliant thermal interface material delivers an impressive 10.0W/mK thermal conductivity, making it suitable for extremely demanding applications.

UniGap 10000NS combines low thermal resistance values with excellent thermal wet-out properties for superb thermal performance. Compliant in nature and naturally tacky on both sides of the material, **UniGap 10000NS** is suitable for use in a wide variety of silicone-sensitive, heat generating electronic applications.

Features

- Non-silicone, ceramic filled thermal gap filling pad
- Thermal conductivity = 10.0W/mK
- Meets RoHs and REACH requirements

Availability

- Standard thicknesses of 0.5mm to 5.0mm
- Supplied as custom die-cut shapes on submission of drawing

Benefits

- High thermal conductivity for efficient maximisation of heat transfer to a heatsink or nearby metal work
- Exceptionally low thermal resistance
- Fills micro air voids between contact surfaces for improved thermal performance

Recommended Uses

- For demanding silicone-sensitive applications
- Thermally coupling any heat generating electrical component to a heatsink or nearby metal work
- For cooling electronic applications in high-performance industries such as automotive and aerospace

Typical Physical Properties

Property (unit)	Test Method	UniGap 10000NS
Colour	Visual	Grey
Thermal Conductivity (W/mK)	Hot Disk	10.0
Hardness (Shore 00)	ASTM D2240	65
Operating Temp. (°C)	-	-40 to +125
Flame Rating	UL94	V-0

Mechanical Information

Property (unit)	Test Method	UniGap 10000NS
Thickness Tolerance (%)	-	± 10
Volume Resistivity (Ω-cm)	ASTM D257	10 ¹⁴
Density (g/cc)	Helium Pycnometer	3.7
Dielectric Constant @ 1 kHz	ASTM D150	9
Outgassing (TML%)	ASTM E595	0.35



www.universal-science.com
UK  +44 (0) 1908 222 211

IT  +39 (02) 395 613 61 FR  +33 (0) 1602 00276



This material is often used in these industries:

